

Rev F1, Page 1/30

#### **FEATURES**

- ♦ Programmable angle resolution from 1 to 256 steps per period
- ♦ Interpolation factors from x0.25 to x64
- ♦ Input frequency to 115 kHz with x64, to 230 kHz with x32, to 460 kHz with x16
- ♦ Latency of less than 1 µs
- ♦ Selectable gain permits single-ended and differential input signals from 10 mV to 1.5 V peak-peak
- ♦ Index gating input with fine adjustable offset
- ♦ Programmable index pulse output position and width
- ♦ Four incremental output modes: quadrature encoder with index, up/down clock, incr./direction, 3 phase commutation
- ♦ Programmable filter and hysteresis
- Direct sensor connection, minimized count of external components
- ♦ Non-volatile setup due to internal EEPROM
- ♦ Fully re-programmable via serial 1- and 2-wire interfaces
- ♦ Power-on reset circuit and on-chip oscillator
- ♦ ESD protection and TTL-/CMOS-compatible outputs
- ♦ Operation at 3.0 V to 5.5 V, from -40 °C to +125 °C

#### **APPLICATIONS**

- ◆ Interpolation IC for position data acquisition from analog sine/cosine sensors
- Optical linear and rotary encoders
- Magneto resistive sensors and encoders

#### **PACKAGES**



24-pin QFN 4 mm x 4 mm x 0.9 mm RoHS compliant

#### **BLOCK DIAGRAM** VDDA VDD NRST PINA CLKSEL +) POWER CLKEXT SYSTEM CLOCK ON LЭН B\_V NINA NB NV iC-TW2 A\_U PINB NA\_NU <del>-(+)-</del> Z\_W į NZ NW L(+)-SIN/D CONVERSION NINB SDAT FILTER PINZ HYSTERESIS SCLK r T GENERATOR $\overline{\mathscr{A}}$ SIGNAL PROCESSING 1W $\vdash \leftarrow \vdash$ NINZ VC REGISTERS BANDGAE INDEX ENABLE GNDA GND



Rev F1, Page 2/30

#### **DESCRIPTION**

iC-TW2's interpolation engine accepts two fully differential sensor bridges delivering sine and cosine input signals to produce a highly interpolated output signal. No further external components are required. Single-ended sensor signals are supported by tying the negative input terminals to the signal reference, usually VDD/2.

iC-TW2 generates one index pulse for every input period. The position in respect to the start of the period as well as the width of the pulse is fully programmable.

There are four different output modes provided, including 3-phase commutation output for brushless DC motors. To meet requirements for a wide range of applications, iC-TW2 is highly programmable.

Two serial interfaces have been included to permit configuration of the device, also accessing the internal EEPROM. Both interfaces allow complete configuration of the device including transfer of setup data to internal registers and the on-chip EEPROM for non-volatile storage.

#### **CONTENTS**

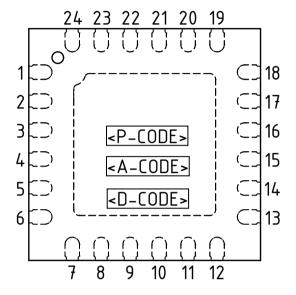
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40
18
18
18
18
19
13
20
20
20
ACCESS 21
2
2
24
24
25
25
ROM 25
26
26
20
27
28
28



Rev F1, Page 3/30

#### **PACKAGING INFORMATION**

#### **PIN CONFIGURATION QFN24-4x4**



#### **PIN FUNCTIONS**

No.	Name	Function
1	VDD	+3 V to +5.5 V Digital Supply Voltage
	ВV	B Signal / V Signal Output
	NB NV	Inverted B / Inverted V Signal Output
4	$A_{\overline{U}}$	A Signal / U Signal Output
5	NA_NU	Inverted A / Inverted U Signal Output
6	GND	Digital Ground
7	$NZ_NW$	Inverted Z/Inverted W Signal Output
8	Z_W	Z Signal / W Signal Output
9	1W	1W-Interface, signal input
	VDDA	+3 V to +5.5 V Analog Supply Voltage
11	GNDA 1	Analog Ground
12	n.c.	Pin not connected
13	PINB	Signal Input B+
	NINB	Signal Input B-
15	CLKSEL	•
16	NRST	External Reset Input (active low)
17	NINA	Signal Input A-
	PINA	Signal Input A+
	VC	1.2 V Reference Voltage Output
20	NINZ	Signal Input Z- (Index)
21		Signal Input Z+ (Index)
	SCLK	2-Wire Interface, clock input
		External Clock Input
24	SDAT	2-Wire Interface, serial data in/out
	TP <sup>2</sup>	Thermal Pad (bottom side)

IC top marking: <P-CODE> = product code, <A-CODE> = assembly code (subject to changes), <D-CODE> = date code (subject to changes);

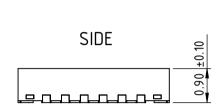
<sup>&</sup>lt;sup>1</sup> GNDA must be wired to GND.
<sup>2</sup> The *Thermal Pad* of the QFN package (bottom side) is to be connected to a ground plane on the PCB which must have GND potential.

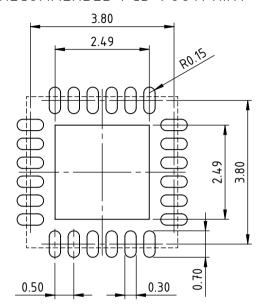


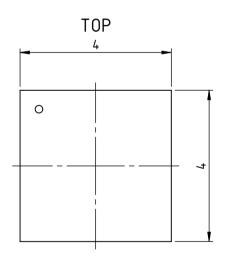
Rev F1, Page 4/30

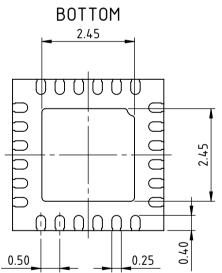
#### **PACKAGE DIMENSIONS**

#### RECOMMENDED PCB-FOOTPRINT









All dimensions given in mm. Tolerances of form and position according to JEDEC MO-220.

drb\_qfn24-4x4-1\_pack\_1, 10:1



Rev F1, Page 5/30

#### **ABSOLUTE MAXIMUM RATINGS**

These ratings do not imply operating conditions; functional operation is not guaranteed. Beyond these ratings device damage may occur.

Item	Symbol	Parameter	Conditions			Unit
No.	-			Min.	Max.	
G001	VDD, VDDA	Voltage at VDD, VDDA	referenced to GND	-0.3	6.0	V
G002	∆VDDA	Voltage Difference VDD vs. VDDA	△VDDA = VDD - VDDA	0	0.5	V
G003	V()	Voltage at PINA, NINA, PINB, NINB, PINZ, NINZ, B_V, NB_V, A_U, NA_U, Z_W, NZ_W, 1W, SDAT, SCLK, CLKSEL, CLKEXT	referenced to GND	-0.3	VDD + 0.5 V	V
G004	I()	Current in PINA, NINA, PINB, NINB, PINZ, NINZ, B_V, NB_V, A_U, NA_U, Z_W, NZ_W, 1W, SDAT, SCLK, CLKSEL, CLKEXT, VC		-20	20	mA
G005	Vd	ESD Susceptibility Of Signal Outputs	HBM, 100 pF discharged through 1.5 kΩ; pins A_U, NA_U, B_V, NB_V, Z_W, NZ_W		1.5	kV
G006	Vd	ESD Susceptibility (remaining pins)	HBM, 100 pF discharged through 1.5 kΩ		1	kV
G007	Tj	Junction Temperature		-40	125	°C
G008	Ts	Storage Temperature		-40	125	°C

#### **THERMAL DATA**

Item	Symbol	Parameter	Conditions				Unit
No.				Min.	Тур.	Max.	
T01	Та	Operating Ambient Temperature		-40		125	°C
T02	Rthja	Thermal Resistance Chip To Ambient	QFN24 surface mounted to PCB, following JEDEC 51		32		K/W



Rev F1, Page 6/30

#### **ELECTRICAL CHARACTERISTICS**

ltem No.	Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Total	Device	I.	1				
001	VDD, VDDA	Permissible Supply Voltage VDD, VDDA		3.0		5.5	V
002	I(VDD, VDDA)	Total Supply Current	VDD = 3.3 V at 0 Hz VDD = 3.3 V at 100 kHz VDD = 5.5 V at 0 Hz VDD = 5.5 V at 100 kHz			5 20 8 40	mA mA mA mA
003	Vc()hi	Clamp-Voltage hi at all pins	Vc()hi = V() - VDD; I() = 10 mA	0.5		1.3	V
004	Vc()lo	Clamp-Voltage lo at all pins	I() = -10 mA	-1.3		-0.3	V
Input	Amplifier PII	NA, NINA, PINB, NINB					,
101	Vin()sig	Permissible Input Voltage Range		1.4		VDD - 1.2	V
102	Step(GC)	Nominal Coarse Gain Step Size			6.0		dB
103	AGabs(GC)	Coarse Gain Absolute Accuracy		-1.0		3.5	dB
104	Step(GF)	Nominal Fine Gain Step Size			0.7		dB
105	AGabs(GF)	Fine Gain Absolute Accuracy		-0.3		0.3	dB
106	CGM	Gain Matching G(CHA)/G(CHB)		0.85		1.15	
107	Vin()os	Input Referred Offset Voltage		-15		15	mV
108	Vout()ossc	Output Referred Offset Correction Step Accuracy		-10		10	mV
109	Step(OFSx)	Nominal Offset Correction Step Size			13		mV
110	Vout()os	Output Referred Offset Voltage		-40		40	mV
111	FR	Permissible Input Frequency; Frequency Ratio FR = f <sub>cal</sub> / f <sub>in</sub>	INTER = 1 64, FREQ = 0 INTER = 1 64, FREQ = 1 INTER = 1 64, FREQ = 2 127 INTER = 65 128, FREQ = 0 INTER = 65 128, FREQ = 1 127 INTER = 129 255 INTER = 0	64 128 256 128 256 256 256			
112	llk()	Input Leakage Current		-50		+150	nA
Oscill							
201	f <sub>cal</sub>	Permissible User Calibrated Oscillator Frequency	measured at pin A_U in calib mode 2 as 1/32; VDD = 3.6 V, Tj = 25 °C VDD = 5.5 V, Tj = 25 °C			25 30	MHz MHz
202	f <sub>osc</sub>	Oscillator Frequency	VDD = 3.0 V, Tj = 25 °C, CLOCK = 0 VDD = 3.0 V, Tj = 25 °C, CLOCK = 31 VDD = 5.5 V, Tj = 25 °C, CLOCK = 0 VDD = 5.5 V, Tj = 25 °C, CLOCK = 31	35 40		25 28	MHz MHz MHz MHz
203	TCosc	Oscillator Frequency Temperature Drift	VDD = 5.0 V +/- 2 %		-0.12	0	%/K
204	VC <sub>osc</sub>	Oscillator Frequency Power Supply Dependency	Tj = 25 °C		10		%/V
205	df <sub>osc</sub>	Osc. Frequency Variation 3.3 V	supply voltage 3.3 V +/-10%, Tj = 25 °C		+/-3		%
206	df <sub>osc</sub>	Osc. Frequency Variation 5 V	supply voltage 5 V +/-10%, Tj = 25 °C		+/-2		%
EEPR	ОМ						
301	Tret	Data Retention Time	Tj = 125 °C Tj = 85 °C	10 100			years
302	Ncycles	Number of Erase/Write Cycles	Tj = 25 °C	1000			
303	Nread	Number of Read Cycles		10 <sup>6</sup>			
Refer	ence Voltage	Output VC					
401	Vref(VC)	Reference Voltage	C <sub>L</sub> = 100 nF, I(VC) = 0 mA	1.15	1.21	1.27	V



Rev F1, Page 7/30

#### **ELECTRICAL CHARACTERISTICS**

Operating conditions: VDD = VDDA = 3.0...5.5 V. Ti = -40...125 °C. unless otherwise stated

Тур.	1.5 3.3 -3 500	V V V PA mV
	3.3 -3 500	V V V μΑ
	3.3 -3 500	V V V μΑ
	500	V μA
	500	
		mV
	1.5	
	1.5	
	3.3	V
		V
		μA
	500	mV
-		-
	0.5 0.4	V V
	-15	mA
	0.3 0.25	V
	140	mA
	4	ns
	4	ns
	10	mA
50		%
25		%
1/ f <sub>core</sub>		
	6	DEG
	20	%
1/2 AArel		%
	VDD	V
	+15	mV
1.5 -1.5		mV mV
	+150	nA
1.8		V
	1 1	1
	25 1/ f <sub>core</sub> 1/2 AArel 1.5 -1.5	50 25 1/ f <sub>core</sub> 6  20  1/2 AArel  VDD +15 1.5 -1.5 +150



Rev F1, Page 8/30

#### **ELECTRICAL CHARACTERISTICS**

Operating conditions: VDD = VDDA = 3.0...5.5 V, Tj = -40...125 °C, unless otherwise stated

Item	Symbol	Parameter	Conditions				Unit
No.				Min.	Тур.	Max.	
2-Wire	Interface S	DAT, SCLK					
B01	Vt()hi	Input Threshold Voltage hi	VDD = 3.3 V +/- 10 % VDD = 5.0 V +/- 10 %			1.5 3.3	V V
B02	Vt()lo	Input Threshold Voltage lo	VDD = 3.3 V +/- 10 % VDD = 5.0 V +/- 10 %	0.8 1.0			V V
B03	lpd()	Input Pull-down Current	V() = 1 VVDD	4			μA
B04	Vpd()	Input Pull-down Voltage	I() = 3 μA			500	mV
B05	Vs()lo	Saturation Voltage lo at SDAT	I() = 2 mA			450	mV
B06	Vs()hi	Saturation Voltage hi at SDAT	Vs()hi = VDD - V(); I() = -2 mA			700	mV
B07	Isc()lo	Short-circuit Current lo at SDAT		3			mA
B08	Isc()hi	Short-circuit Current hi at SDAT				-2.5	mA
B09	fclk(SCLK)	Permissible Clock Frequency SCLK	scales with oscillator frequency timing, see Table 32			1.25	MHz
B10	tbusy()e2p	Max. Duration of EEPROM access	scales with oscillator frequency timing, see Table 32			20	ms
1-Wire	Interface 1	w					•
C01	Vt()hi	Input Threshold Voltage hi	VDD = 3.3 V +/- 10 % VDD = 5.0 V +/- 10 %			1.5 3.3	V V
C02	Vt()lo	Input Threshold Voltage lo	VDD = 3.3 V +/- 10 % VDD = 5.0 V +/- 10 %	0.8 1.0			V V
C03	lpu()	Input Pull-up Current	V() = 0VDD - 1 V			-3	μA
C04	Vpu()	Input Pull-up Voltage	Vpu() = VDD - V(), I() = -3 μA			500	mV

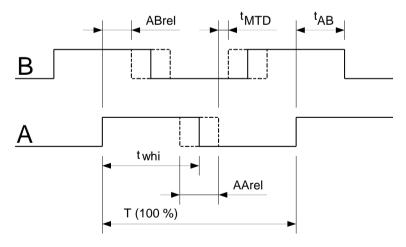


Figure 1: Relative phase distance



Rev F1, Page 9/30

#### **REGISTER MAP**

Registe	er Map							
Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Device	Indentification	n						
0x00		IDA	(3:0)			IDB	(3:0)	
Operati	ng Modes							
0x01		RESET (P. 20)	CALIB1 (P. 17)	STARTU	P(1:0)(P. 20)	DIR (P. 13)	MODE	(1:0) <sub>(P. 13)</sub>
Interpol	ation Rate							
0x02				INTER	(7:0) <sub>(P. 13)</sub>			
Index P	osition							
0x03				IPOS(	7:0) <sub>(P. 14)</sub>			
Index W	/idth							
0x04				IWIDTH	I(7:0) <sub>(P. 14)</sub>			
Convers	sion Settings							
0x05	GRANU- LAR <sub>(P. 26)</sub> FREQ(6:0) <sub>(P. 18)</sub>							
0x06					FILTER	(1:0) <sub>(P. 18)</sub>	HYST(	1:0) <sub>(P. 18)</sub>
Gain an	d Offset							
0x07		GFB(1	<b>:0)</b> (P. 12)	GFA(1	:0) (P. 12)		GC(2:0) (P. 12)	
80x0					OFSA(	,		
0x09					OFSB(	5:0) <sub>(P. 12)</sub>		
Bias an	d Oscillator T	rimming						
0x0A		VC(1	:0) <sub>(P. 26)</sub>		C	LOCK(4:0) <sub>(P.</sub>	17)	
Index C	omputation a	nd Miscellane	ous					
0x0B		OFSZ(	3:0) <sub>(P. 17)</sub>		EN_MON (P. 26)	CLKDLY (P. 26)	CLKDIV (P. 18)	CLKMODE (P. 26)
Reserve	ed and Calibra	ation			I		L	
0x0C				Reserved <sub>(P. 26</sub>	)			CALIB2
0x0D				Reser	ved <sub>(P. 26)</sub>			
EEPRO	M Control							
0x0E	EE_READ (P. 26)	EE_WRITE			Reser	ved <sub>(P. 26)</sub>		
Test Re	gister	<del>'</del>						
0x0F				MONITO	R(7:0) <sub>(P. 26)</sub>			

Table 4: Register Map



Rev F1, Page 10/30

#### **PROGRAMMING**

Input Stage GC:			tification
GC. GFA/B: OFSA/B:	Fine gain control on channel A/B (P. 12)  Offset control on channel A/B (P. 12)	IDA: IDB:	Major Device Revision (P. 19) Minor Device Revision (P. 19)
MODE: DIR:	Output mode selection (P. 13) Count direction (P. 13)	Start Up STARTUP: RESET:	
INTER: IPOS: IWIDTH:	Interpolation rate selection (P. 13) Index pulse position (P. 14) Index pulse width selection (P. 14)		terface And EEPROM Access . Page 21 EEPROM store command (P. 25)
Index Gatin	<b>g</b> Page 16		Page 26
Calibration CALIB1: CALIB2: OFSZ: CLOCK:	Calibration mode 1 select (P. 17) Calibration mode 2 select (P. 17) Index comparator offset control (P. 17) Oscillator tune (P. 17)	VC: CLKMODE:	A/B output edge granularity control (P. 26) Reference voltage fine tuning (P. 26) Clock source selection (P. 26)
Configuration FREQ: CLKDIV: HYST: FILTER:	Maximum input frequency (P. 18) Master clock divider (P. 18) Hysteresis control (P. 18) Datapath filter control (P. 18)	EN_MON: MONITOR: EE_READ:	Clock distribution delay line selection (P. 26) Position data monitor control (P. 26) Monitor register (P. 26) EEPROM read command (P. 26)



Rev F1, Page 11/30

#### **DESCRIPTION OF INTERPOLATION**

iC-TW2 is a monolithic A/D converter which converts sine/cosine sensor signals with a selectable resolution

and hysteresis into angle position data. The interpolation function is shown in Figure 2.

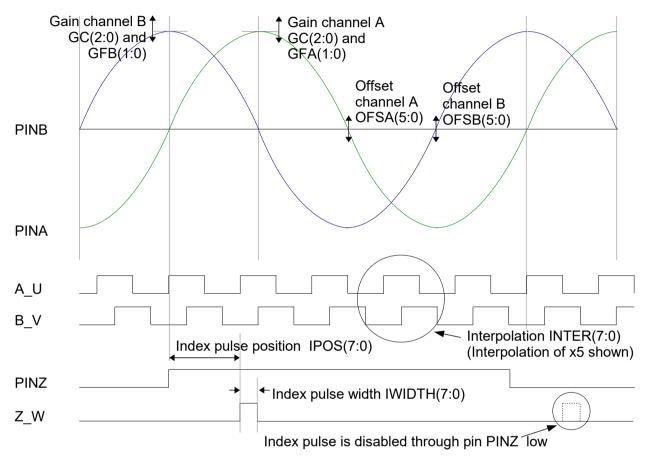


Figure 2: Interpolation function

#### Interpolation vs. Resolution

There is a difference between interpolation factor and resolution. Resolution (interpolation rate) is determined by the sum of edges at the incremental outputs (AB quadrature output) within one input signal period.

Dividing the resolution by the existing edges of the sine and cosine signals (=4) equals to the interpolation fac-

tor. The interpolation factor equals to the the resolution divided by 4.

#### Example:

An interpolation factor of x8 brings a resolution of 32 (edges). To operate with an interpolation factor of 8 configure INTER(7:0) to 32.



Rev F1, Page 12/30

#### **INPUT STAGE**

#### **Programmable Gain Amplifier**

A programmable gain amplifier (PGA) with output referred offset adjustment is used as input stage, shown in Figure 3. The coarse gain is common for both channel A and B and is programmed through register GC(2:0). Fine tuning gain is applied individually to channel A and B by programming registers GFA(1:0) and GFB(1:0) respectively.

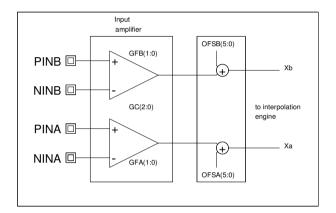


Figure 3: Input stage

GC(2:0)	Addr. 0x07; bit 2:0 R/W
Code	Input Signal Range V <sub>IN peak-peak</sub> [V <sub>IN peak-peak diff.</sub> ]
000	400 mV - 750 mV [800 mV - 1.5 V] 400 mV max. @VDD = 3.0 V
001	200 mV - 400 mV
010	100 mV - 200 mV
011	50 mV - 100 mV
100	25 mV - 50 mV
101	12.5 mV - 25 mV
110	5 mV - 12.5 mV
111	not defined (defaults to eeprom setting)

Table 5: Coarse gain control of channel A/B

GFA(1:0)	Addr. 0x07; bit 4:3	R/W
GFB(1:0)	Addr. 0x07; bit 6:5	R/W
Code	Fine Gain (defaults to eeprom setting)	
00	0 dB	
01	0.7 dB	
10	1.4 dB	
11	2.1 dB	

Table 6: Fine gain control of channel A/B

#### Offset Adjustment

Offset adjustment is provided at the output of the input amplifier. It is individually programmed through register OFSA(5:0) and OFSB(5:0). Adjustment is made in steps of 13 mV and the corresponding register val-

ues are sign magnitude encoded. Input referred offset becomes gain dependent and is defined as follows:

$$V_{\text{OFS (A input referred)}} = \frac{13 \, mV * OFSA(5:0)}{GC(2:0)}$$

OFSA(5:0)	Addr. 0x08; bit 5:0	R/W
OFSB(5:0)	Addr. 0x09; bit 5:0	R/W
Code	Offset Correction (defaults to eeprom setting)	
111111	maximum negative adjust: -403 mV	
111110	-390 mV	
100001	-13 mV	
100000	no correction	
000000	no correction	
000001	13 mV	
011110	390 mV	
011111	maximum positive adjust: 403 mV	

Table 7: Offset control of channel A/B

Consider Table 8 regarding the relationship between coarse gain, permissible peak-to-peak input amplitude and the resulting offset correction range.

Coarse	Input Signal Range	Input-referred	Input-ref.
Gain		offset corr. range	offset step
GC(2:0)	V <sub>IN peak-peak</sub>	V <sub>OFS max</sub>	$dV_{OFS}$
0	400 mV - 750 mV	±806 mV	26 mV
	400 mV max. @3 V		
1	200 mV - 400 mV	± 403 mV	13 mV
2	100 mV - 200 mV	± 202 mV	6.5 mV
3	50 mV - 100 mV	± 101 mV	3.25 mV
4	25 mV - 50 mV	± 50 mV	1.63 mV
5	12.5 mV - 25 mV	± 25 mV	0.81 mV
6	5 mV - 12.5 mV	± 12.6 mV	0.41 mV

Table 8: Input signal and offset correction ranges.

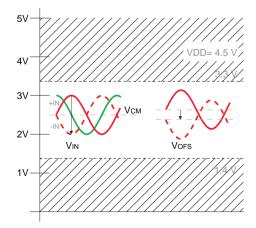


Figure 4: Permissible input voltage range at VDD = 5 V +/- 10 %.



Rev F1, Page 13/30

#### **OUTPUT MODES**

The iC-TW2 provides four different output modes, which are configured by programming bits MODE(1:0) of register 0x01. Modes 0, 1 and 2 are incremental modes whereas mode 3 is a 3-phase commutation output for brushless DC motors. Consider Figure 5 for a comparison of the 3 incremental output modes.

MODE(1:0)	Addr. 0x01; bit 1:0	R/W
Code	Function, defaults to eeprom setting	
00	AB quadrature (mode 0)	
01	up / dn (mode 1)	
10	inc / dir (mode 2)	
11	3 phase commutation (mode 3)	

Table 9: Output mode selection

In increment / direction mode the count direction can be inverted via control bit DIR of register 0x01.

DIR	Addr. 0x01; bit 2	R/W
Code	Function, defaults to eeprom setting	
0	Normal count direction	
1	Inverted count direction	

Table 10: Count direction selection

INTER (7:0)	Adr 0x02, Bit 7:	0 R/W	
Code	STEP Angle Steps Per Period	IPF Interpolation Factor	fin()max Max. Permissible Input Frequency *
0x00	256	64	115 kHz**
0x01	1	0.25	460 kHz
0x02	2	0.5	460 kHz
0x03	3	0.75	460 kHz
0x04	4	1	460 kHz
0x05	5	1.25	460 kHz
			460 kHz
0x3C	60	15	460 kHz
0x3D	61	15.25	460 kHz
0x3E	62	15.5	460 kHz
0x3F	63	15.75	460 kHz
0x40	64	16	460 kHz
0x41	65	16.25	230 kHz
0x42	66	16.5	230 kHz
0x43	67	16.75	230 kHz
0x44	68	17	230 kHz
0x45	69	17.25	230 kHz
			230 kHz
0x7C	124	31	230 kHz
0x7D	125	31.25	230 kHz
0x7E	126	31.5	230 kHz
0x7F	127	31.75	230 kHz
0x80	128	32	230 kHz
0x81	129	32.25	115 kHz
0x82	130	32.5	115 kHz
0x83	131	32.75	115 kHz
0x84	132	33	115 kHz
0x85	133	33.25	115 kHz
			115 kHz
0xFA	250	62.5	115 kHz
0xFB	251	62.75	115 kHz
0xFC	252	63	115 kHz
0xFD	253	63.25	115 kHz
0xFE	254	63.5	115 kHz
0xFF	255	63.75	115 kHz
Notes	*) For f <sub>osc</sub> = 29.4 MHz, FREQ = 0, CLKDIV = 0. **) 115 kHz is fin()max for commutation operation (MODE = 3).		

Table 11: Converter resolution



Rev F1, Page 14/30

#### AB Quadrature And Up/Down and Incr/Dir Modes

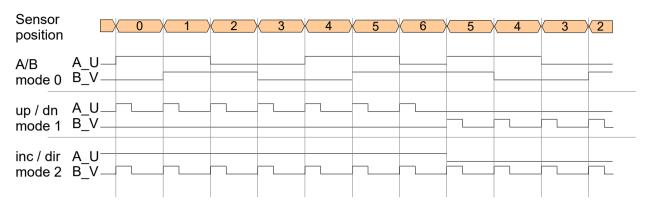


Figure 5: Incremental output modes (mode 0, 1, 2)

IPOS(7:0)	Addr. 0x03; bit 7:0 R/W
Code	Function, defaults to eeprom setting
0	No offset
1	1 increment offset
2	2 increments offset
	Index pulse will be shifted by IPOS(7:0) increments. Programmed value is within the range of 0 to INTER(7:0) - 1.
255	255 increments offset
Note:	A fixed phase relation to A/B is guaranteed only with STARTUP(1:0) = 0b10 ('ABSOLUTE") or STARTUP(1:0) = 0b11 ('BURST").

Table 12: Index pulse position

IWIDTH(7:0	) Addr. 0x04; bit 7:0	R/W
Code	Function, defaults to eeprom setting	
0	disable pulse generation	
1	1 increment width	
2	2 increments width	
Any other value n	Index pulse will extend over IWIDTH(7:0) increments.	
	Programmed value is within the range of 0 to INTER(7:0) - 1.	
255	255 increments width	

Table 13: Index pulse width selection



Rev F1, Page 15/30

#### 3 Phase Commutation Mode

The 3 phase commutation output (mode 3) is shown in Figure 6. It is important that register INTER(7:0) is programmed with the value 0x00 in order for the commutation mode to work. The mode = 3 requires an internal interpolation INTER(7:0) of 256. Register IPOS(7:0) is used to accurately position the commutation. IWIDTH(7:4) and IWIDTH(3:0) is subsequently used to fine tune V and W in respect to U. All used offsets within the commutation mode (mode 3) as are IPOS(7:0), IWIDTH(3:0) and IWIDTH(7:4) operate in this step width of  $1.4^{\circ}$ . There is no other pole count commutation possible to configure as the described 3 phase commutation.

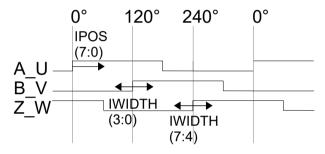


Figure 6: 3-Phase commutation output (mode 3)

IPOS(7:0)	Addr. 0x03; bit 7:0	R/W
Code	Function, defaults to eeprom setting	
0	0°	
1	1.40°	
2	2.81°	
	Programmed value is within the range of 0 to INTER(7:0) - 1.	
255	358,59°	

Table 14: UVW commutation signal position offset

IWIDTH(3:0)	) Addr. 0x04; bit 3:0	R/W
Code	V output offset, defaults to eeprom setting	
0111	9.84°	
0010	2.81°	
0001	1.40°	
0000	0°	
1111	-1.40°	
1110	-2.81°	
1111	11.25°	

Table 15: V commutation signal position offset

IWIDTH(7:4)	) Addr. 0x04; bit 7:4	R/W
Code	W output offset, defaults to eeprom setting	
0111	9.84°	
0010	2.81°	
0001	1.40°	
0000	0°	
1111	-1.40°	
1110	-2.81°	
1111	11.25°	

Table 16: W commutation signal position offset



Rev F1, Page 16/30

#### **INDEX GATING**

The iC-TW2 can interface to a wide range of index gating sources. Most commonly used are the digital Hall sensor and the MR sensor bridge.

The digital Hall sensor provides a large swing input signal to the iC-TW2. Depending on the polarity of the Hall it is either connected to pin NINZ or PINZ. Most Hall sensors use an open drain stage pulling the output low in the presence of a magnetic field. The unused terminal PINZ or NINZ should be biased to an adequate mid voltage level to guarantee good noise margin. The iC-TW2 provides a constant 1.21 V at pin VC that can be used for this purpose (refer to Figure 7).

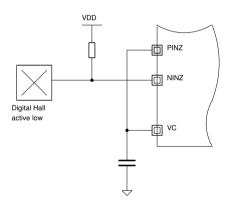


Figure 7: Digital Hall sensor index configuration

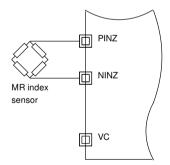


Figure 8: MR sensor index configuration

An MR sensor differential bridge can also be used to gate the index. Typically, the MR sensor provides a small signal amplitude. In addition, residual side lobes are present that can trigger double indexing. The

iC-TW2 provides offset control capability to fine tune the threshold voltage of the index comparator. This greatly simplifies end product calibration as variation in sensor offset can be compensated for.

Figure 9 shows a correctly set threshold when using an MR gating sensor. The side lobes are below the threshold line and no parasitic triggering occurs.

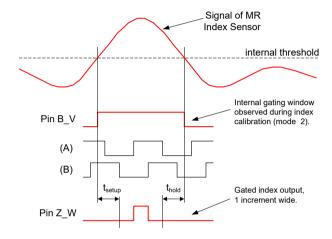


Figure 9: Index gating and calibration

Index gating should be calibrated at sine/cosine input frequencies below  $5\,\text{kHz}$  to minimize the effect of latency. Timings shown in Table 17 are valid for input frequencies below  $5\,\text{kHz}$  and  $f_{\text{system}}$  of  $25\,\text{MHz}$ . Once the timings are satisfied according to Table 17, correct operation is guaranteed up to the maximum input frequency as specified in Table 26 on page 19.

Parameter	Description	Condition *	min
t <sub>setup</sub>	Index window setup time before rising edge of Z_W	no filter 8 average 16 average	0.4 μs 0.5 μs 0.7 μs
t <sub>hold</sub>	Index window hold time after falling edge of Z_W	no filter 8 average 16 average	0.4 μs 0.5 μs 0.7 μs

\*) According to register FILTER(1:0) f<sub>system</sub> = 25 MHz, all timings scale with f<sub>system</sub>. Refer to Table 26 for more information

Table 17: Index gating and timing



Rev F1, Page 17/30

#### **CALIBRATION**

In order to facilitate system gain and offset calibration, two calibration modes can be enabled by either setting bit CALIB1 of register 0x01 or CALIB2 of register 0x0C.

CALIB2	Addr. 0x0C; bit 0	R/W
CALIB1	Addr. 0x01; bit 5	R/W
CALIB2;1	Function, defaults to eeprom setting	
00	Normal operation, no calibration	
01	A/B gain and index calbration	
10	Oscillator and index window calibration	
11	Not permitted	

Table 18: Calibration modes

#### A/B gain and offset calibration

In calibration mode 1 the SIN/COS input is directly passed through two zero-cross comparators to output pin A and B respectively. In addition, the sum of the input signals

$$\frac{SIN + COS}{\sqrt{2}}$$

is also fed through a comparator and driven on pin Z.

The actual calibration process must be carried out in several steps.

- 1. Select proper coarse gain by programming register GC(2:0). Set GFA(1:0) and GFB(1:0) to 0.
- 2. Adjust offset register OFSA(5:0) and OFSB(5:0) until output A and B are 50% duty cycle.
- 3. Adjust fine gain register GFA(1:0) and GFB(1:0) until output Z is equidistant between output A and B.
- 4. Repeat step 1 and 2 until no more improvement can be achieved.

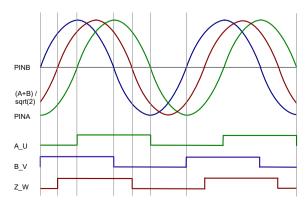


Figure 10: Output signals for A/B gain and offset adjustment in calibration mode 1.

#### Oscillator and index window calibration

When calibration mode 2 is enabled, the output of the index comparator is driven on pin B\_V. In conjunction with the actual index output on pin Z\_W, the gating window can be centered around the output pulse (see Figure 9). Fine offset adjustment applied to the input of the index comparator is possible through OFSZ(3:0) which is sign magnitude encoded. This is beneficial when using small amplitude index sources such as an MR sensor.

Simultaneously, the oscillator frequency  $f_{\text{osc}}/32$  can be observed on pin A\_U. Register CLOCK(4:0) is used to tune the oscillator to its desired frequency.

OFSZ(3:0)	Addr. 0x0B; bit 7:4	/W
Code	Function, defaults to eeprom setting	
1111	maximum negative adjust, -10.5 mV	
1110	-9 mV	
1001	-1.5 mV	
1000	no correction	
0000	no correction	
0001	1.5 mV	
0110	9 mV	
0111	10.5 mV	
1	calibration mode 2 activated	

Table 19: Index comparator offset control

CLOCK(4:0)	Addr. 0x0A; bit 4:0	R/W
Code	Function, defaults to eeprom setting	
00000	Slowest clock	
11111	fastest clock	

Table 20: Oscillator tuning



Rev F1, Page 18/30

#### **CONFIGURATION DEPENDENCIES**

This section describes the dependencies between the chip configuration and the system's performance. It is vital to understand the implication of system parameters to be able to tune the iC-TW2 for full performance. It is especially important to correctly program register FREQ(6:0), since this directly affects accuracy and maximum allowed input frequency.

Selecting	configuration	parameters
-----------	---------------	------------

To select a proper configuration follow the outlined procedure below. Refer to Table 26 for reference.

- 1. Determine the maximum input frequency  $f_{\text{in}()\text{max}}$  as required by the application.
- 2. Calculate  $f_{core}$  based on  $f_{in()max}$  and resolution INTER(7:0).
- 3. Select  $f_{system}$  based on the accuracy requirements. Accuracy is a function of resolution INTER(7:0) and clock scaling FREQ(6:0). Always use the highest accuracy possible to still satisfy  $f_{in()max}$ .
- 4. Determine  $f_{\text{osc}}$ . Selecting the slowest possible  $f_{\text{osc}}$  lowers power consumption and improves jitter performance.

#### **Clock tuning**

- 1. Observe  $f_{\rm osc}/32$  on pin A\_U during calibration mode 2.
- 2. Use CLOCK(4:0) to tune the oscillator to the desired  $f_{cal}$  frequency. ( $f_{pinA} = f_{osc}/32$ )
- 3. Be aware that the oscillator can have as much as 20 % frequency variation over the operating temperature range (-40 °C to 125 °C). The oscillator runs slower at higher temperatures. To guarantee performance at 125 °C it is necessary to tune the oscillator to typ. 12 % higher frequency at room temperature of 25 °C.

#### **Accuracy modes**

The converter resolution INTER(7:0) in conjunction with the clock scaling FREQ(6:0) define iC-TW2's accuracy mode. Based on the selected accuracy mode other system parameters are defined as shown in Table 26.

INTER(7:0)	FREQ(6:0)	Accuracy	Theoretical
		Mode	Absolute
			Accuracy
129 to 256; 0	0 to 127	High accuracy	±2.8°
65 to 128	0	Medium acc.	±5.6°
	1 to 127	High accuracy	±2.8°
1 to 64	0	Low accuracy	±11.2°
	1	Medium acc.	±5.6°
	2 to 127	High accuracy	±2.8°

Table 21: Accuracy modes

CLKDIV	Addr. 0x0B; bit 1 R/V	٧
Code	Function (defaults to eeprom setting)	
0	$f_{\text{system}} = f_{\text{osc}}$	
1	f <sub>system</sub> = f <sub>osc</sub> / 2	
Note	It is recommended to use the divider when support for high input frequencies is not required.	t

Table 22: Master clock divider

FREQ(6:0)	Addr. 0x05; bit 6:0	R/W
Code	Clock scaling (defaults to eeprom setting)	
0x00	$f_{core} = f_{system}$	
	$f_{core} = f_{system} / (1 + FREQ(6:0))$	
0x7F	f <sub>core</sub> = f <sub>system</sub> / 128	

Table 23: Clock scaling

HYST(1:0)	Addr. 0x06; bit 1:	0 R/W
	Function (defaults to eepr	om setting)
Code	High accuracy	Medium / low accuracy
00	no hysteresis	no hysteresis
01	±1.4°	±2.8°
10	±2.81°	±5.6°
11	±5.63°′	±11.3°

Table 24: Hysteresis control

FILTER(1:0)	Addr. 0x06; bit 3:2 R/W
Code	Function (defaults to eeprom setting)
00	filter disabled
01	Average of 8 samples
10	Average of 16 samples
11	undefined
Notes	It is recommended to enable the filter in almost all cases as it removes loop instability noise. However, enabling the filter increases the Sin/Cos input to A/B output latency (see Table 26 for details).

Table 25: Datapath filter control



Rev F1, Page 19/30

Description	Parameter	Requirement or relationship	Control bit
Oscillator Frequency	f <sub>osc</sub> [Hz]		CLOCK(4:0)
Calibrated Osc. Frequ.	f <sub>cal</sub> [Hz]	<30 MHz at VDD = 5.5 V, <25 MHz at VDD = 3.6 V; see Elec. Char. item 201	
System Clock	f <sub>system</sub> [Hz]	$f_{\text{system}} = f_{\text{osc}}$ , if CLKDIV = 0 $f_{\text{system}} = f_{\text{osc}}/2$ , if CLKDIV = 1	CLKDIV
Core Clock	f <sub>core</sub> [Hz]	$f_{core} = f_{system} / (1 + FREQ(6:0))$	FREQ(6:0)
Front-end Frequency Limit*	f <sub>front</sub> [Hz]	f <sub>front</sub> = f <sub>system</sub> / 256, if High Accuracy f <sub>front</sub> = f <sub>system</sub> / 128, if Medium Accuracy f <sub>front</sub> = f <sub>system</sub> / 64, if Low Accuracy	FREQ(6:0) INTER(7:0)
	f <sub>front</sub> is the maximum sin/co	os input frequency which can be processed by the front-	end.
Back-end Frequency Limit*	f <sub>back</sub> [Hz]	$f_{\text{back}} = f_{\text{core}} / \text{INTER}(7:0)$	INTER(7:0)
	f <sub>back</sub> is the maximum sin/c	os input frequency which can be processed by the A/B of	jenerator back-end.
Max. Input Frequency	f <sub>in()max</sub> [Hz]	$f_{in()max} = min(f_{front}, f_{back})$	
	The permissible max. sin/o	cos input frequency is determined by f <sub>back</sub> or f <sub>front</sub> , whate	ever means the lower limit.
Max. A/B Output Frequency	f <sub>out(AB)max</sub> [Hz]	$f_{\text{out(AB)max}} = f_{\text{core}} / 4$ $f_{\text{out(AB)max}} = 0.25 / t_{\text{edge}}$	
A/B Edge Separation, Min. Transition Distance	t <sub>edge</sub> ,	$t_{\text{edge}} = t_{\text{MTD}} = 1 / f_{\text{core}}$	
A/B Edge Granularity	t <sub>gran</sub>	t <sub>gran</sub> = 1 / f <sub>system</sub>	
Sin/Cos to A/B Output Latency	t <sub>latency</sub> [µs]	10 / f <sub>system</sub> [MHz] + 0.2, if no filter 18 / f <sub>system</sub> [MHz] + 0.2, if 8 sample average 26 / f <sub>system</sub> [MHz] + 0.2, if 16 sample average	FILTER(1:0)
*) Parameter does not rep	resent a functional IC param	eter, paramter introduced for calculation purposes only.	

Table 26: Configuration dependencies

#### **DEVICE IDENTIFICATION**

IDA(3:0)	Addr. 0x00; bit 7:4	R/W
Code	Function, Major device identification	
	Mask Programmed Value Identifies Maj	or Revision

IDB(3:0)	Addr. 0x00; bit 3:0	R/W
Code	Function, Minor device identification	
	Mask Programmed Value Identifies Minor Re	vision

Table 27: Major device revision Table 28: Minor device revision



Rev F1, Page 20/30

#### **START UP**

#### Power-On-Reset

The iC-TW2 contains a built-in Power-On-Reset (POR) circuitry. The POR keeps the iC-TW2 in reset as long as the applied power supply voltage does not allow reliable operation. Once the power supply ramps up above 1.8 V, the POR releases the reset and the iC-TW2 starts the configuration cycle. 20 ms after the device goes out of reset, normal operation begins.

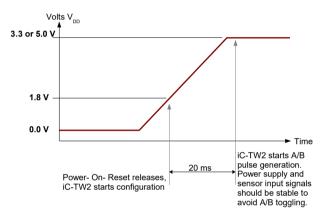


Figure 11: Power supply ramp-up

To avoid A/B output toggling it is important that the power supply and the input signals are stable as soon as normal operation begins. In applications with a slowly rising power supply, it might be necessary to connect an external RC reset to pin NRST to prolong the reset. In applications where startup A/B toggling is acceptable, no precaution must be taken as the iC-TW2 will properly power up on an indefinitely slow supply rise time.

The iC-TW2 startup behaviour is controlled by programming the two control bits STARTUP(1:0) in register 0x01. Three possible startup configurations are allowed, shown in Figure 12. The default behaviour must be specified by the eeprom.

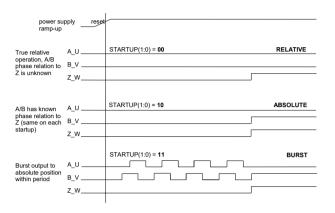


Figure 12: Startup behaviour

STARTUP(1	<b>:0)</b> Addr. 0x01; bit 4:3 R/W
Code	Function
00	<b>RELATIVE</b> A/B output signals are kept low during startup. This resembles true relative operation since there is no relationship between A/B levels and sensor position (and therefore Z output) on startup.
01	Reserved
10	ABSOLUTE  A/B output signals are phase-related to Z output.  A/B output levels are defined by the absolute sensor position within a period. The register <i>IPOS</i> can be used to program the desired A/B to Z phase relationship.
11	BURST The absolute sensor position within the period is output by an A/B burst.

Table 29: Startup sequence selection

#### Reset

A control bit RESET is provided to block any burst A/B pulses during chip reconfiguration by a microcontroller. While RESET is set A/B/Z output generation is stopped. Access to the interface and register bank is not affected.

RESET	Addr. 0x01; bit 6	R/W
Code	Function	
0	A/B/Z output according to STARTUP default	
1	A/B/Z output halted following reset	
Notes	RESET = 1 may be programmed to the EEPF can be used temporarily to avoid spurious A/ output pulses when reconfiguration by an exmicrocontroller is intended.	B/Z

Table 30: Restart of interpolation engine following power-on or software initiated reset.



Rev F1, Page 21/30

#### 1W-/2W-INTERFACE AND EEPROM ACCESS

#### **Memory map**

Figure 13 depicts the iC-TW2 memory map and interface diagram. A 2-wire read/write interface and a 1-wire write-only interface allow access to the register bank and the EEPROM bank. The register bank is 8 bits wide and it is used to control all chip functionality. Refer to section "Register Map" on page 9 for an overview of all registers.

**NB:** The 1W-Interface and the 2W-interface do not feature a timeout.

The EEPROM bank on the other hand is 32 bits wide. Address 0x05, 0x06 and 0x07 (3 \* 4 bytes = 12 bytes) can be used to store user data such as product serial numbers, calibration and manufacturing information.

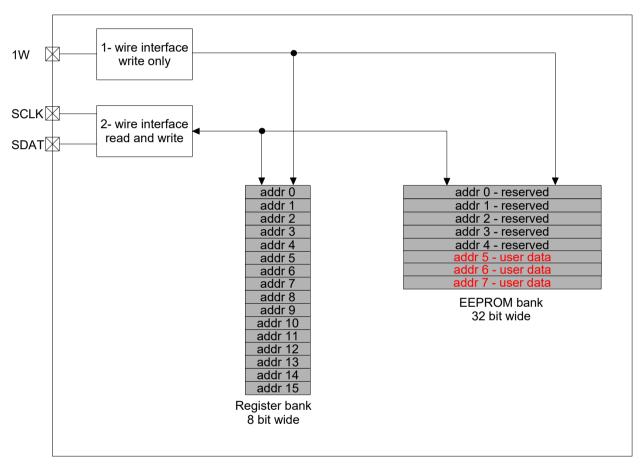


Figure 13: Memory map

#### 2W-Interface

The first control interface is a standard 2-wire serial interface. It uses an external clock and bidirectional data line. It allows read and write access to all internal registers as well as access to the user EEPROM. The interface consists of two pins, a dedicated input SCLK, the shifting clock and SDAT for bidirectional serial data.

The interface handles four types of access requests:

1. Write to control register

- 2. Read from control register
- 3. Write to EEPROM register (including block access and erase)
- 4. Read from EEPROM register

Control register access is shown in Figure 14 (write) and Figure 15 (read) respectively. If SDAT is **00** after the start bit a write access is requested. The data word d(7:0) will be written into register a(4:0). Please note that a(4) is always 0 since the iC-TW2 only has 16 addressable registers.



Rev F1, Page 22/30

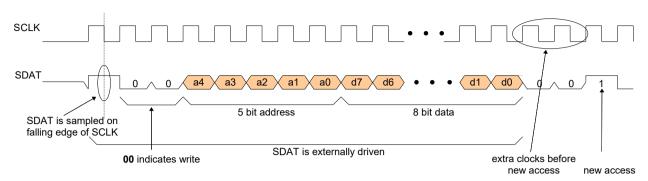


Figure 14: Register bank write access on 2W-Interface

On a register read access the register content is shifted out on SDAT. A read access is indicated by SDAT 10 after the start bit. There is an idle clock required between the last address bit a(0) and the first data bit d(7) returned on SDAT. This clock cycle is used to avoid any bus contention while turning around the bus driver.

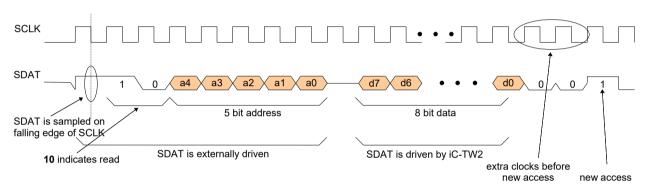


Figure 15: Register bank read access on 2-wire interface

Write access to the EEPROM follows the procedure depicted in Figure 16. A start bit is followed by four command bits c-1-e-b. The encoding of the command bits is shown in Table 31. The most useful command

is **0100** which performs an erase followed by a write therefore allowing the user to write a new value to the EEPROM with only one interface access.

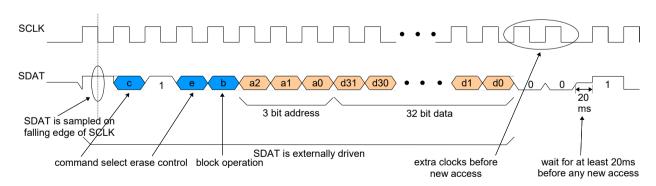


Figure 16: EEPROM write access on 2-wire interface



Rev F1, Page 23/30

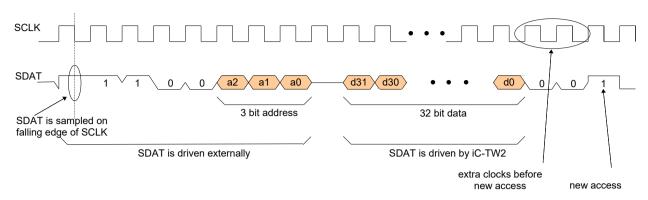


Figure 17: EEPROM read access on 2-wire interface

The 3 bit address a(2:0) selects the EEPROM register to write to (Figure 13). Each EEPROM register is 32 bits wide, therefore 32 data bits d(31:0) are sent across the interface. At least 20 ms delay is required after every transaction before any new access can start.

EEPROM read access is shown in Figure 17. The start bit is followed with the 4 bit read command **1100** and the 3 bit address a(2:0). An idle clock cycle is used to avoid any contention on SDAT while reversing data flow direction. Finally d(31:0) is shifted out on SDAT. EEPROM read access is slow.

At least one extra clock with SDAT low is required after every transaction on the 2-wire interface before a new access is started. The interface will not work correctly if this clock cycle is omitted.

Refer to Table 32 regarding timings requirements. Please note, given timing specifications scale with  $f_{\rm osc}$ . For instance, with  $f_{\rm osc}$  = 22 MHz timings are reduced by 10%.

E	EEPROM Commands					
С	1	е	b	Description	Purpose	
0	1	0	0	Erase followed by write	Normal EEPROM programming	
0	1	0	1	Block erase followed by block write	Test only	
0	1	1	0	Write	Special production environment	
0	1	1	1	Block write	Test only	
1	1	0	0	Read. Please refer to Figure 17 for more details		
1	1	0	1	Reserved. Do not use this command		
1	1	1	0	Erase	Test only	
1	1	1	1	Block erase	Special production environment	

Table 31: EEPROM Commands



Rev F1, Page 24/30

#### 2W-Interface timing

The timing of the 2W-Interface is dependent on the type of access performed. Register bank access and EEPROM write access can be performed at full speed. EEPROM read access requires a slow SCLK. Also a 20 ms delay is required after every EEPROM write access before a new transaction of any kind is started (this includes read and write to the register bank).

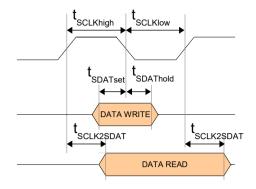


Figure 18: 2W-Interface timing diagram

2W-Interface timing						
Parameter	Description	Condition	min	max		
t <sub>SCLKhigh</sub>	SCLK high	EEPROM read access	8 µs			
		Any other access	400 ns			
t <sub>SCLKlow</sub>	SCLK low	EEPROM read access	8 µs			
		Any other access	400 ns			
t <sub>SDATset</sub>	SDAT setup before falling edge of	Write access	100 ns			
	SCLK					
t <sub>SDAThold</sub>	SDAT hold after falling edge of	Write access	100 ns			
	SCLK					
t <sub>SCLK2SDAT</sub>	SCLK to SDAT valid delay	EEPROM read access	5 ns	7µs		
	after rising edge of SCLK	Any other access	5 ns	105 ns		
Notes	Timings given above are valid for $f_{osc} = 20 \text{ MHz}$ and scale with $f_{osc}$ .					
	For instance, f <sub>osc</sub> = 22 MHz reduces all given timings by 10%.					

Table 32: 2W-Interface timing

#### **Trouble Shooting**

To transfer iC-TW2's configuration data from RAM to EEPROM command EE\_WRITE must be used.

Power must be available over the whole process taking approx. 100 ms. The suggested 1  $\mu$ F bypass capacitors are important. GUI button <Read EPPROM> must deliver reliable contents.

To help iC-TW2's 2-wire interface not to receive disturbances, an external pull-down resistor at SCLK (e.g.  $1\,\mathrm{k}\Omega$ ) may be used to support its internal pull-down keeping the idle state.

iC-TW2's interface does not feature a timeout, and there is no enable pin (as for SPI). A certain risk for loosing the synchronisation does exist. For instance, connecting a programming cable may introduce edges to SCLK, so that the interface is not synchronized for communication anymore.

In case of communication problems try to reset iC-TW2 by pulling pin NRST low. When doing so, there should be no communication.

Another solution can be to clear the interface by applying approx. 50 clock pulses to SCLK while SDAT is held low.



Rev F1, Page 25/30

#### 1W-Interface

The 1W-Interface provides a write-only access port to the register bank. It is intended as a minimal configuration interface to program the internal EEPROM during in-field service or production. An infrared phototransistor can directly connect to the pin to build a cost effective wireless write port. The input bit stream is pulse-width modulated (or duty-cycle modulated) as

shown in Figure 19. A zero-bit is encoded as a short low followed by a long high. A one-bit is encoded as a long low followed by a short high. The modulated signal is independent of the receiver or transmitter clock frequency. Since the iC-TW2 uses a free-running oscillator, it is important to implement a robust, frequency-insensitive protocol.

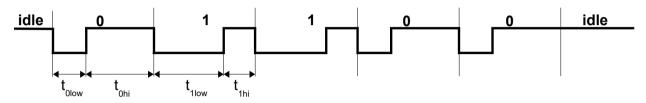


Figure 19: Pulse width modulated bit stream

The interface timing is specified in the following Table.

Parameter	Description	min	max
t <sub>Olow</sub>	Low time bit 0	40 μs	100 μs
t <sub>0hi</sub>	High time bit 0	120 $\mu$ s	200 μs
t <sub>1low</sub>	Low time bit 1	120 μs	200 μs
t <sub>1high</sub>	High time bit 1	40 μs	100 μs

Table 33: 1W-Interface timing

#### 1W-Interface write sequence

Figure 20 describes the write sequence to the register bank, which uses the same protocol as the 2W-Interface. On an idle wire, a write sequence is initiated by writing a start bit (1) followed by the write command (00) followed by the address and register data. At the end of the sequence, a stop-bit (0) is required.

1W-Interface write access to the EEPROM bank is shown in Figure 21. The 4 bit EEPROM command after the start bit is decoded in Table 31.

#### Writing the register bank to the EEPROM

To permanently store a configuration in the internal EEPROM the following procedure should be followed.

- 1. The 1W-/2W-Interface is used to fully write the desired configuration into the register bank.
- A logic one is written to bit EE\_WRITE of register 0x0E. This will initiate a write sequence which copies all registers into the internal EEPROM. A complete write takes 100 ms. During this time, no access to the register bank through either the

- 1W-/2W-Interface is allowed or data corruption might occur.
- Finally the register content, after a device reset and configuration, should be verified to ensure a successfull EEPROM write sequence.

Writing the registers to the EEPROM using EE\_WRITE takes up to 100 msec. During this access to the register bank either through the 1W- or 2W-Interface is prohibited. Any access will corrupt data written to the EEPROM.

EE_WRITE	Addr. 0x0E; bit 6 W
Code	Function, bit is automatically reset upon completion of operation
0	Normal operation (default)
1	Store registers into EEPROM

Table 34: EEPROM store command

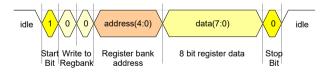


Figure 20: 1W-Interface register bank write sequence



Figure 21: 1W-Interface EEPROM write sequence



Rev F1, Page 26/30

#### **TEST MODES**

The iC-TW2 provides various control bits located in different registers to enable or disable certain test modes. The majority of these is only required for extended chip testing capability, others are required for production test.

GRANULAF	Addr. 0x05; bit 7	R/W
Code	Function, test mode only	
0	normal operation	
1	test mode only	

Table 35: A/B output edge granularity control

VC(1:0)	Addr. 0x0A; bit 6:5	R/W
Code	Function, test mode only	
	register must be set to 0 for correct device functionality	

Table 36: Reference voltage fine tuning

CLKMODE	Addr. 0x0B; bit 0	R/W
Code	Function, test mode only	
0	Select comparator clock default	
1	Select direct oscillator clock	

Table 37: Clock source select

CLKDLY	Addr. 0x0B; bit 2	R/W
Code	Function	
0	Normal operation	
1	Add clock delay	

Table 38: Clock distribution delay line selection

Enabling the position monitor will allow access to the internal absolute period position. The position can be read through register 0x0F. This is considered a test mode and should not be used during normal operation.

EN_MON	Addr. 0x0B; bit 3	R/W
Code	Function	
0	Position monitor disabled default	
1	Monitor enabled	

Table 39: Position monitor control

MONITOR(7	: <b>0)</b> Ad	dr. 0x0F;	bit 7:0	R/W
Code	Function			
	Access to only!	the intern	al absolute perio	od position. RT

Table 40: Monitor register

EE_READ	Addr. 0x0E; bit 7 W		
Code	Function		
0	Normal operation		
1	Read all iC-TW2 registers from the EEPROM. Bit is automatically reset upon completion. Not required during normal operation since this is done automatically on start-up.		

Table 41: EEPROM read command register

#### Production test control bits

Production test control bits are reserved bits. Do not use the production test control bits during normal operation. Keep reserved bits "0".

Reserved	Addr. 0xC; bit 7:1	R/W
Reserved	Addr. 0xD; bit 7:0	R/W
Reserved	Addr. 0xE; bit 2:0	R/W
Code	Function	
0	Normal operation	
1	Do not use or alter to	

Table 42: Test modes



Rev F1, Page 27/30

#### **TYPICAL APPLICATIONS**

The circuit in Figure 22 depicts a typical application. Differential sensor signals (or differential sine/cosine encoder signals) are directly connected to the iC-TW2.

Index gating is single ended active low as is frequently the case when using a Hall switch. The VC signal of 1.21 V is used to bias the positive input PINZ. It is recommended to decouple pin VC with a small capacitor when it is used as a reference. When pin VC is left unconnected, no capacitor is required.

Although iC-TW2 features internal pull-down current sources to define default pin levels, an additional pull-down resistor at pin SCLK can be recommended to reduce its disturbance and cross talk sensitivity.

When using pins NRST (low active reset input) and 1W (programming) is not intended, R1 and R2 can be replaced by shorts to VDD.

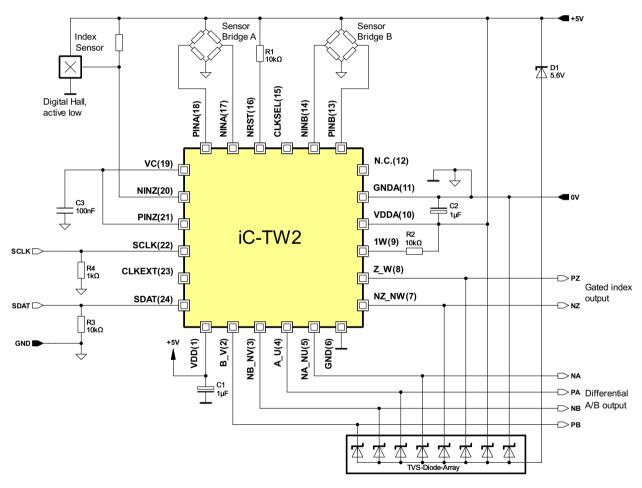


Figure 22: Application circuit with differential sin/cos sensor bridges and a Hall switch for index sensing.



Rev F1, Page 28/30

#### **PCB LAYOUT GUIDELINES**

The iC-TW2 is a noise sensitive mixed signal device, which requires careful PCB layout considerations. Violating the layout guidelines can result in poor performance. Please consider Figure 23.

Power pins VDDA (pin 10) and VDD (pin 1) must be decoupled with  $1\,\mu F$ .

Trace length to VDD pins must be no longer than 3 mm.

The decoupling caps can be placed on the bottom side of the PCB directly connecting it to the iC-TW2 pads using vias.

Ground pins GND (pin 6) and GNDA (pin 11) must be tied to the center exposed pad.

The exposed pad is then directly connected to the PCB ground plane using several vias.

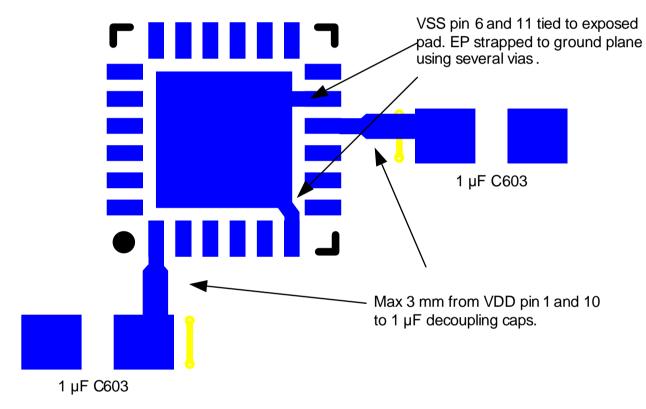


Figure 23: PCB layout guidelines

#### **REVISION HISTORY**

Rel.	Rel. Date*	Chapter	Modification	Page
F1	2021-06-04	PACKAGING INFORMATION	Pinout figure updated, package dimensions added	3cf
		ELECTRICAL CHARACTERISTICS	Items 112 and 904 added Items 501, 502, 601, 602, B01, B02, and C01, C02: min/max limits reversed	6cf
		CONFIGURATION DEPENDENCIES	Table 26: correction of formula f <sub>out(AB)max</sub>	19

<sup>\*</sup> Release Date format: YYYY-MM-DD



Rev F1, Page 29/30

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Rev F1, Page 30/30

#### **ORDERING INFORMATION**

Туре	Package	Order Designation
iC-TW2	24-pin QFN, 4 mm x 4 mm, thickness 0.9 mm, RoHS compliant	iC-TW2 QFN24
Evaluation Board	PCB approx. 100 mm x 80 mm	iC-TW2 EVAL TW2_2D

Please send your purchase orders to our order handling team:

Fax: +49 (0) 61 35 - 92 92 - 692 E-Mail: dispo@ichaus.com

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